

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of claims:

- 1-11. (canceled)
12. (currently amended) A circuit board assembly comprising:
a circuit board comprising a board pad;
a component package comprising a terminal having a planar base area; aligned
with the board pad;
the terminal including a J-hook shaped, elongated member, having an outer
surface and a cross section area, extending from the terminal base; and
a solder deposit having a hourglass shape, covering the board pad and the outer
surface of the elongated member
13. (currently amended) The circuit board assembly of Claim [[10]] 12, wherein the board pad has a surface area greater than the cross section area of the elongated member.
- 14-15. (canceled)
16. (currently amended) The circuit board assembly of Claim [[10]] 12, wherein the component package comprises a Quad Flat No-lead (QFN) package.
17. (currently amended) The circuit board assembly of Claim [[10]] 12, wherein the component package comprises a Small Outline No-lead (SON) package.
- 18-20. (canceled)

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21. (currently amended) The circuit board assembly of claim [[1]] 12, in which the solder deposit has a length that is approximately the length of the elongated member.
22. (previously presented) The circuit board assembly of claim 21, in which the cross section of the solder deposit along its length is smaller than the planar base area of the terminal.